

LASER PROCESSING APPARATUS AND METHOD OF OBSERVING LASER BEAM

ABSTRACT OF THE DISCLOSURE

A laser processing apparatus includes a laser oscillator configured to oscillate a laser, a first condenser configured to condense a laser beam emitted from the laser oscillator, and irradiate a workpiece held on a chuck table with the laser beam, and an observing unit configured to observe a state of a condensing point of the laser beam applied to the workpiece in a pseudo manner. The observing unit includes a second condenser configured to condense the laser beam in a direction different from a direction of a holding surface of the chuck table, a microscope configured to magnify the laser beam condensed by the second condenser, and an imaging element configured to observe the condensing point of the laser beam magnified by the microscope.

[Fig. 2]